

Data Sheet Issue:- 2

# Insulated Gate Bi-Polar Transistor Type T0900EB45A

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V <sub>CES</sub>	Collector – emitter voltage	4500	V
V <sub>DC link</sub>	Permanent DC voltage for 100 FIT failure rate.	2800	V
V <sub>GES</sub>	Peak gate – emitter voltage	±20	V

	RATINGS	MAXIMUM LIMITS	UNITS
I <sub>C(DC)</sub>	DC collector current, IGBT	900	А
I <sub>CRM</sub>	Repetitive peak collector current, t <sub>p</sub> =1ms, IGBT	1800	А
I <sub>F(DC)</sub>	Continuous DC forward current, Diode	900	А
I <sub>FRM</sub>	Repetitive peak forward current, t <sub>p</sub> =1ms, Diode	1800	А
I <sub>FSM</sub>	Peak non-repetitive surge $t_p=10ms$ , $V_{RM}=60\%V_{RRM}$ , Diode (Note 4)	14.2	А
I <sub>FSM2</sub>	Peak non-repetitive surge t <sub>p</sub> =10ms, V <sub>RM</sub> ≤10V, Diode (Note 4)	15.6	А
P <sub>MAX</sub>	Maximum power dissipation, IGBT (Note 2)	7.1	kW
(di/dt) <sub>cr</sub>	Critical diode di/dt (note 3)	2000	A/µs
Tj	Operating temperature range.	-40 to +125	°C
T <sub>stg</sub>	Storage temperature range.	-40 to +125	°C

Notes: -

- 1) Unless otherwise indicated  $T_j = 125^{\circ}C$ .
- 2)  $T_{sink} = 25^{\circ}C$ , double side cooled.

3) Maximum commutation loop inductance 200nH.

4) Half-sinewave,  $125^{\circ}CT_{j}$  initial.

## **Characteristics**

### **IGBT** Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
	Collector – emitter saturation voltage	-	2.8	3.2	$I_C = 900A, V_{GE} = 15V, T_j = 25^{\circ}C$	V
V <sub>CE(sat)</sub>		-	3.6	4.0	$I_{C} = 900A, V_{GE} = 15V$	V
V <sub>T0</sub>	Threshold voltage	-	-	1.4	Current range: 200 0000	V
r⊤	Slope resistance	-	-	2.9	Current range: 300 – 900A	mΩ
V <sub>GE(TH)</sub>	Gate threshold voltage	-	5.2	-	$V_{CE} = V_{GE}, I_C = 90 \text{mA}$	V
ICES	Collector – emitter cut-off current		15	35	$V_{CE} = V_{CES}, V_{GE} = 0V$	mA
I <sub>GES</sub>	Gate leakage current	-	-	±10	$V_{GE} = \pm 20 V$	μA
Cies	Input capacitance	-	140	-	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$	nF
t <sub>d(on)</sub>	Turn-on delay time	-	1.7	-		μs
t <sub>r</sub> (V)	Rise time	-	3.5	-	I <sub>C</sub> =900A, V <sub>CE</sub> =2800V, di/dt=1500A/μs	μs
Q <sub>g(on)</sub>	Turn-on gate charge	-	7	-	$V_{GE} = \pm 15V$ , L <sub>s</sub> =200nH	μC
Eon	Turn-on energy	-	6.3	-	$R_{g(ON)}=6\Omega, R_{g(OFF)}=21\Omega, C_{GE}=90nF$	J
t <sub>d(off)</sub>	Turn-off delay time	-	4.2	-	Integral diode used as freewheel diode	μs
t <sub>f</sub> (I)	Fall time	-	2.6	-	(Note 3 & 4)	μs
Q <sub>g(off)</sub>	Turn-off gate charge	-	8	-		μC
E <sub>off</sub>	Turn-off energy	-	4.3	-		J
I <sub>SC</sub>	Short circuit current	-	3000	-	$V_{GE}$ =+15V, $V_{CC}$ =2800V, $V_{CEmax}$ $\leq V_{CES}$ , $t_p$ $\leq$ 10µs	А

## **Diode Characteristics**

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
V <sub>F</sub>	Forward voltage	-	3.7	4.0	I <sub>F</sub> = 900A, T <sub>j</sub> =25°C	V
		-	3.9	4.2	I <sub>F</sub> = 900A	V
V <sub>To</sub>	Threshold voltage	-	-	2.27	0	V
r <sub>T</sub>	Slope resistance	-	-	2.15	Current range 300-900A	mΩ
I <sub>rm</sub>	Peak reverse recovery current	-	800	-	I <sub>F</sub> = 900A, V <sub>GE</sub> = -15V, di/dt=1500A/µs	Α
Qrr	Recovered charge	-	1000	-		μC
t <sub>rr</sub>	Reverse recovery time, 50% chord	-	1.8	-		μs
Er	Reverse recovery energy	-	1.25	-		J

### Thermal Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
R <sub>thJK</sub>	Thermal resistance junction to sink, IGBT	-	-	14	Double side cooled	K/kW
		-	-	23	Collector side cooled	K/kW
		-	-	37	Emitter side cooled	K/kW
R <sub>thJK</sub>	Thermal resistance junction to sink, Diode	-	-	26	Double side cooled	K/kW
		-	-	41	Cathode side cooled	K/kW
		-	-	78	Anode side cooled	K/kW
F	Mounting force	25	-	35	Note 2	kN
Wt	Weight	-	1.2	-		kg

Notes:-

1) Unless otherwise indicated  $T_j=125^{\circ}C$ .

2) Consult application note 2008AN01 for detailed mounting requirements

3)  $C_{GE}$  is additional gate – emitter capacitance added to output of gate drive

4) Figures 6 to 9 are obtained using integral diode as freewheeling diode



## <u>Curves</u>

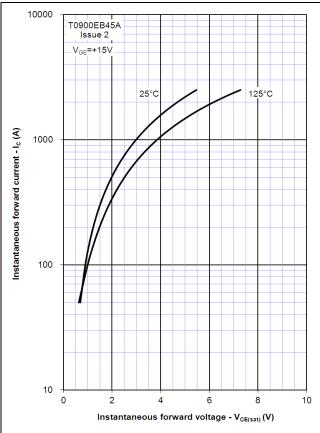
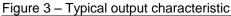


Figure 1 – Typical collector-emitter saturation voltage characteristics



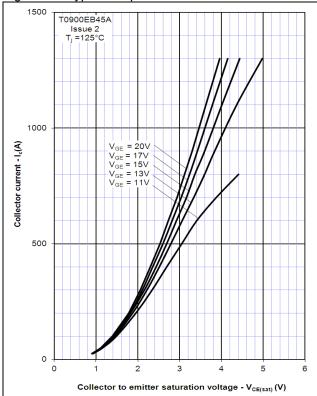


Figure 2 – Typical output characteristic

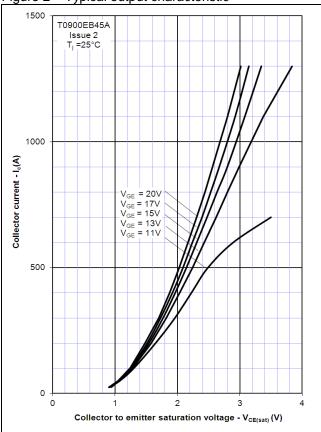
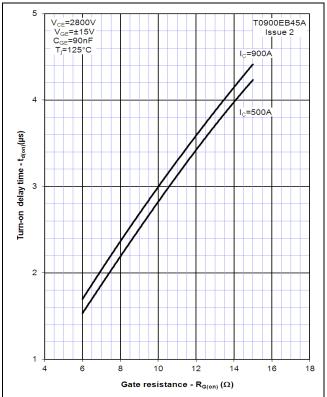


Figure 4 – Typical turn-on delay time vs gate resistance





## resistance 10 T0900EB45A Issue 2 V<sub>CE</sub>=2800V I<sub>c</sub>=900A Ŭ<sub>GE</sub>=±15∨ 9 C<sub>GE</sub>=90nF T<sub>j</sub>=125°C \_I<sub>C</sub>=500A 8 delay time - t<sub>d(off)</sub>(µs) 7 Turn-off 6 5 4 3 10 50 20 60 30 40 Gate resistance - $R_{G(off)}(\Omega)$

Figure 5 - Typical turn-off delay time vs. gate



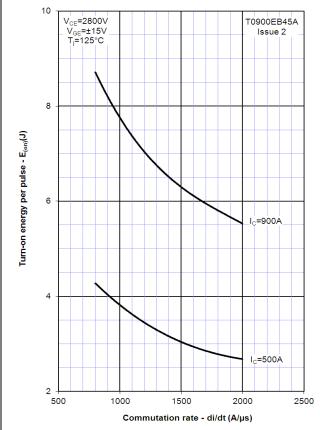


Figure 6 – Typical turn-on energy vs. collector current

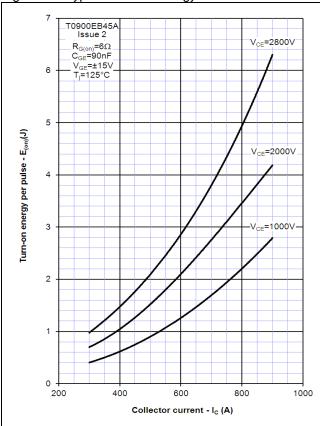
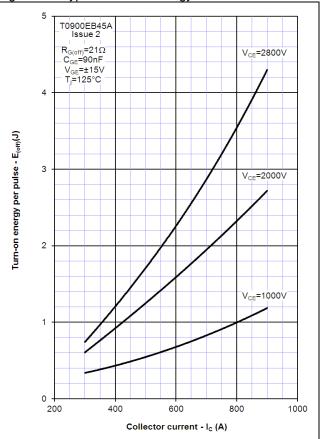
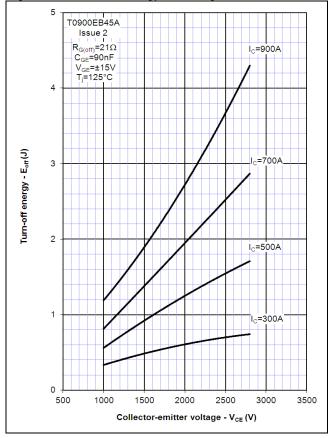


Figure 8 - Typical turn-off energy vs. collector current



Data Sheet T0900EB45A Issue 2





#### Figure 9 - Turn-off energy vs voltage

Figure 11 – Typical diode forward characteristics

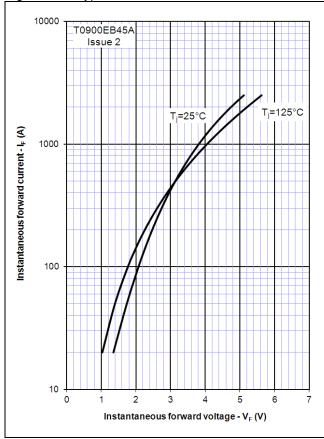


Figure 10 - Safe operating area

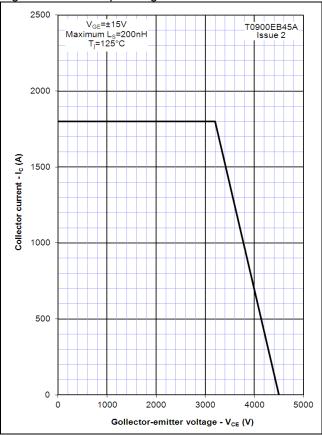
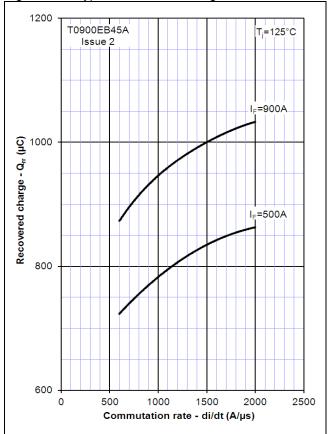


Figure 12 – Typical recovered charge





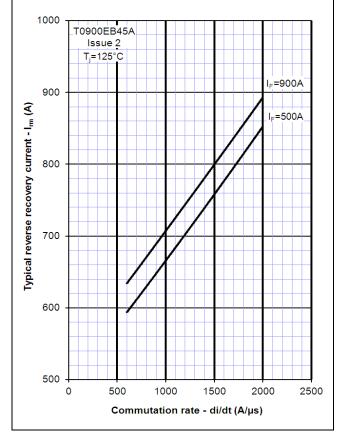
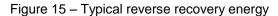


Figure 13 – Typical reverse recovery current



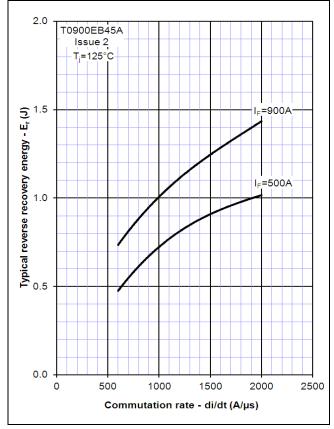


Figure 14 – Typical reverse recovery time

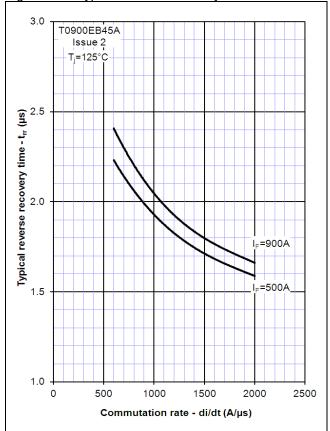
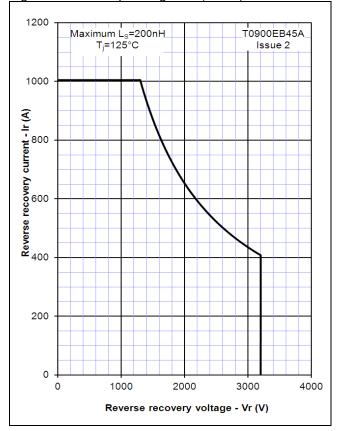
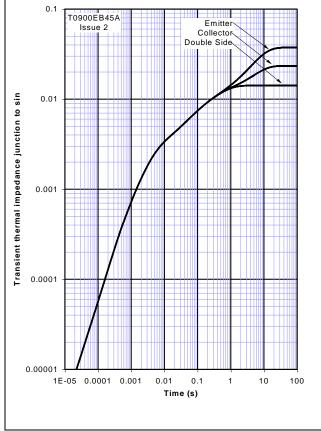


Figure 16 - Safe operating area (Diode)

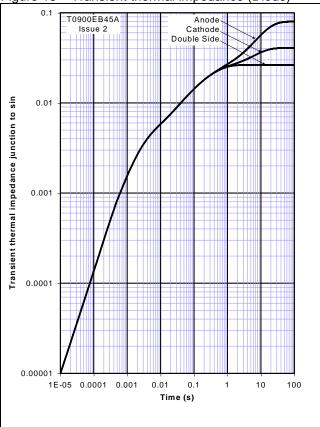






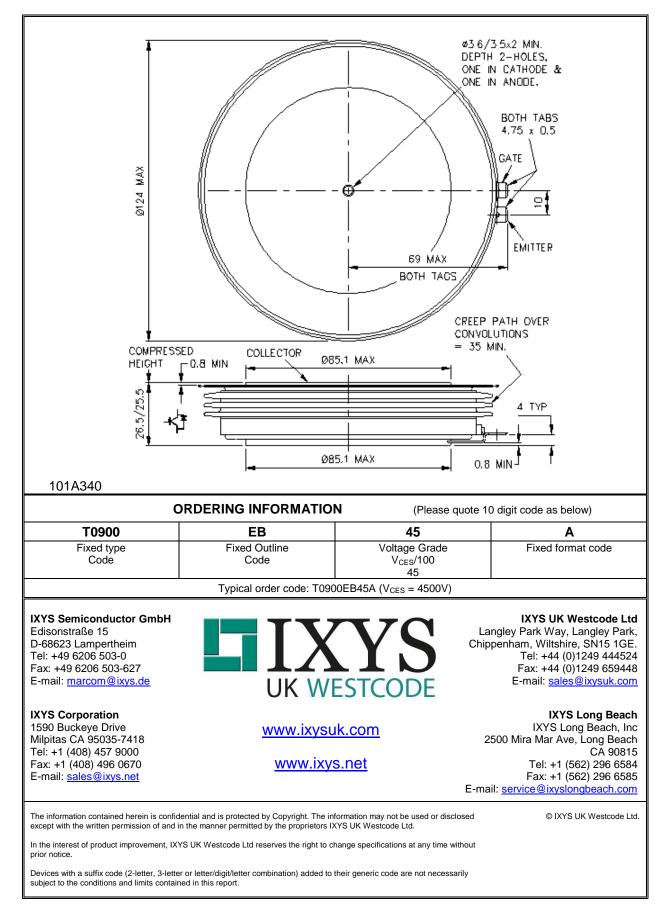
## Figure 17 – Transient thermal impedance (IGBT)

Figure 18 – Transient thermal impedance (Diode)





## **Outline Drawing & Ordering Information**





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